

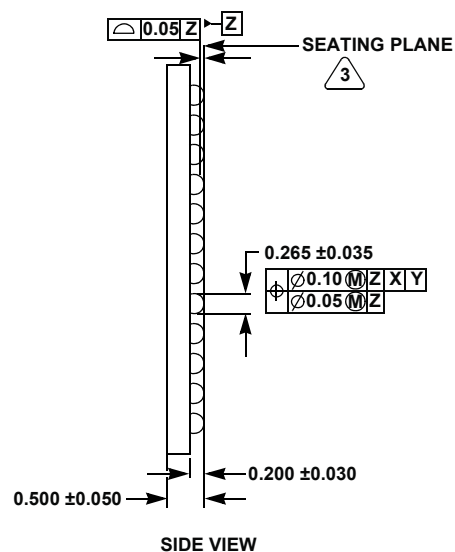
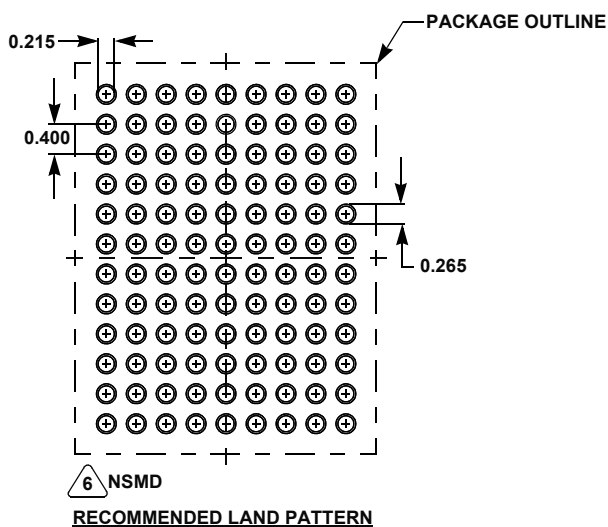
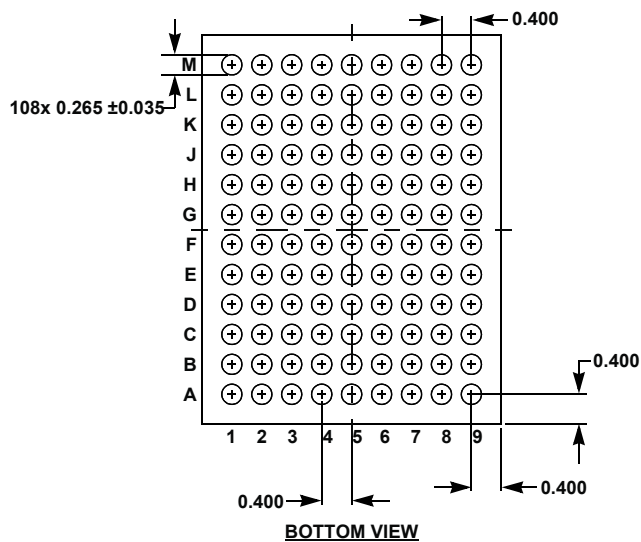
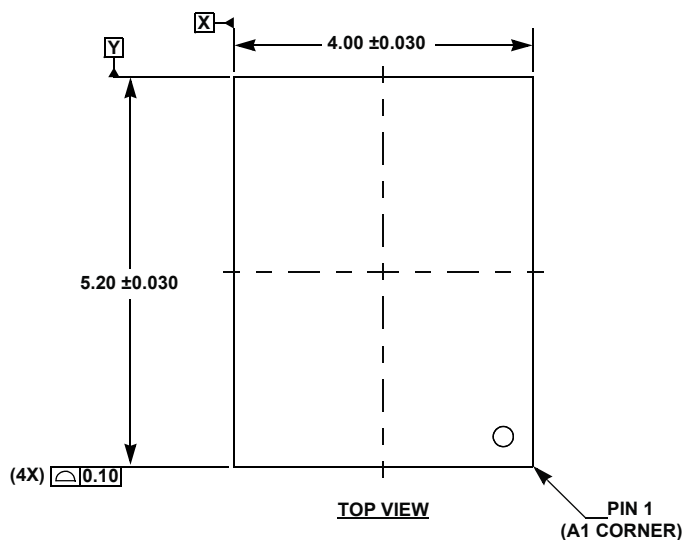
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### W9x12.108

108 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

Rev 0, 1/16



#### NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerance per ASMEY 14.5 - 1994.
- Primary datum  $\triangle Z$  and seating plane are defined by the spherical crowns of the bump.
- Dimension is measured at the maximum bump diameter parallel to primary datum  $\triangle Z$ .
- Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).